Docket No.

197802US-2S

IN RE APPLICATION OF: Wakako MORIYAMA ET AL.

SERIAL NO: 09/670,520

FILED:

**SEPTEMBER 26, 2000** 

FOR:

METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICES USING THERMAL NITRIDE FILMS

AS GATE INSULATING FILMS

ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

SIR:

Transmitted herewith is an amendment in the above-identified application.

- No additional fee is required
- Small entity status of this application under 37 C.F.R. §1.9 and §1.27 is claimed.
- Additional documents filed herewith:

Marked-up Copy of Supplemental Amendment

The Fee has been calculated as shown below:

CLAIMS	CLAIMS REMAINING		HIGHEST NUMBER PREVIOUSLY PAID	NO. EXTRA CLAIMS	RATE	CALCULATIONS
TOTAL	15	MINUS	22	0	× \$18 =	\$0.00
INDEPENDENT	6	MINUS	6	0	× \$84 =	\$0.00
	☐ MULTIPLE DEPENDENT CLAIMS + \$280 =  TOTAL OF ABOVE CALCULATIONS				+ \$280 =	\$0.00
					\$0.00	
, ,		□ Reduction by 50% for filing by Small Entity				\$0.00
		□ Recordation of Assignment + \$40 =			\$0.00	
					TOTAL	\$0.00

A check in the amount of 

is attached.

- Please charge any additional Fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.
- If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136, and any additional fees required under 37 C.F.R. §1.136 for any necessary extension of time may be charged to Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

OBLON, SPIVAK, McCLELLAND,

MAIER & NEUSTADT, P

Gregory J. Maier

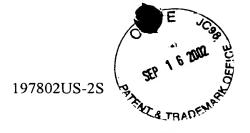
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IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF

:

WAKAKO MORIYAMA ET AL

: EXAMINER: LEE, G. D.

SERIAL NO: 09/670,520

FILED: SEPTEMBER 26, 2000

: GROUP ART UNIT: 2825

FOR: METHOD FOR MANUFACTURING

SEMICONDUCTOR DEVICES

USING THERMAL NITRIDE FILMS AS GATE INSULATING FILMS

RECLIVED
SEP 19 2002

## **SUPPLEMENTAL AMENDMENT**

ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

SIR:

Supplemental to the amendment filed July 25, 2002, please amend this application as follows:

## IN THE CLAIMS

Please amend Claim 10 to read as follows:1

10. (Twice Amended) A semiconductor device manufacturing method comprising:

forming a gate insulating film in an oxynitride form on a main surface of a

semiconductor substrate;

forming gate electrodes on the gate insulating film;

<sup>&</sup>lt;sup>1</sup>A marked-up copy of the changes made to the claims is attached.